

OEM Silicon Pressure Die

Accustable SM30F Family (Replaces SM30D)

Description

The SM30F is a silicon micro-machined, piezoresistive pressure sensing die. This device is available with a full-scale range of 5 to 150 PSI. Both open-bridge and closed-bridge versions are available. This sensor is ideal for OEM and high-volume applications.

Provided in die form, these sensors can be mounted on ceramic on a variety of substrates or packages as part of an OEM system. They also may be packaged into proprietary or application specific sensor lines.

The SM30F die are electrically probed, diced, inspected and shipped on tape. Electronic wafer maps are provided with each wafer. For additional shipping options, contact TE connectivity.

Features

- Improved-stability sensor with an integrated field shield
- Qualified operating temperature range: -40°C to 150°C
- Small size 1.34 x 1.34 mm
- Differential or gauge configuration
- Available 5, 15, 30, 80, 150 PSI
- Ratiometric with supply voltage up to 5.5 V
- Qualified using Grade 0 AEC-Q100 automotive standards
- Manufactured according to ISO9001 and ISO/TS 16949 standards
- RoHS & REACH compliant

Applications

Medical	Industrial	Automotive
Patient Monitors	Industrial Controls	Diesel Particulate Filter
Blood Pressure Monitors	Compressors & Pumps	Exhaust Gas Recirculation
Oxygen Concentrators	Pressure Switches	Automotive Systems
Fluid Evacuation	Oil-Filled Packages	
Ventilators		

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Absolute Maximum Ratings

No.	Characteristic	Symbol	Minimum	Typical	Maximum	Units
1	Excitation Voltage ^(a)	V _{DO}	-	-	5.5	V
2	Operating Temperature	T _{OP}	-40	-	+150	°C
3	Storage Temperature ^(a)	T _{STG}	-55	-	+150	°C
4	ESD Rating – Human body model	V _{ESD}	-	-	2	kV

Notes:

a) The device can only be driven with the supply voltage connected to the pins as shown.

NO.	Product Number	Operating Pressure	Proof Pressure (P _{PROOF}) ^(b)	Burst Pressure (P _{BURST}) ^(b)
5	30F-HND-005S-0000A 30F-HND-005S-0000B	0 to 5 PSI	25 PSI	40 PSI
6	30F-HND-015S-0000A 30F-HND-015S-0000B	0 to 15 PSI	45 PSI	75 PSI
7	30F-HND-030S-0000A 30F-HND-030S-0000B	0 to 30 PSI	90 PSI	150 PSI
8	30F-HND-080S-0000A 30F-HND-080S-0000B	0 to 80 PSI	240 PSI	320 PSI
9	30F-HND-150S-0000A 30F-HND-150S-0000B	0 to 150 PSI	300 PSI	450 PSI

Notes:

b) Tested on a sample basis. The burst and proof pressure values are limited by pressure applied to the backside of the die. The burst and proof pressure values are higher than shown here when pressure is applied to the topside of the die.

Operating Characteristics for SM30F

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The operating characteristics are based on packaged die. The sensor performance may vary depending on the die attach material and process. The die attach material and process should minimize the stress transferred to the sensor die.

The sensor can be operated with the highest pressure applied to the topside of the die (topside operation) or the highest pressure applied to the backside of the die (backside operation). With topside operation, increasing topside pressure will result in an increasing sensor output.

Operating Characteristics table for-SM30F die

All parameters are specified at Vdd = 5.00 V supply voltage at 25°C, unless otherwise noted.

No.	Characteristic	Symbol	Minimum	Typical	Maximum	Units	
10	Span (FS P _{RANGE})	V _{SPAN}	5, 15, 80 PSI ^(d)	60	90	120	mV
			30, 150 PSI ^(d)	55	80	105	
11	Zero Offset	V _{ZERO}	-45	-10	25	mV	
12	TC Span ^(d, e, f)	TCS	-0.24	-0.20	-0.155	%/°C	
13	TC Zero Offset ^(d, e, f)	TCZ	-75	-	75	μV/°C	
14	TC Resistance ^(d, e, f)	TCR	0.24	0.285	0.33	%/°C	
15	Linearity - Topside ^(d, f, g)	NL _{TS}	-0.15	<±0.10	0.15	%FS	
16	Linearity – Backside	NL _{BS}	5 PSI ^(d, f, h)	-0.3	<±0.2	0.3	%FS
			15, 30, 80, 150 PSI ^(d, f, h)	-0.15	<±0.10	0.15	
17	Bridge Resistance	R _B	4	5	6	kΩ	
18	Pressure Hysteresis ^(d)	P _{HYS}		<±0.1		%FS	
19	Thermal Hysteresis ^(d, e)	T _{HYS}		<±0.2		%FS	

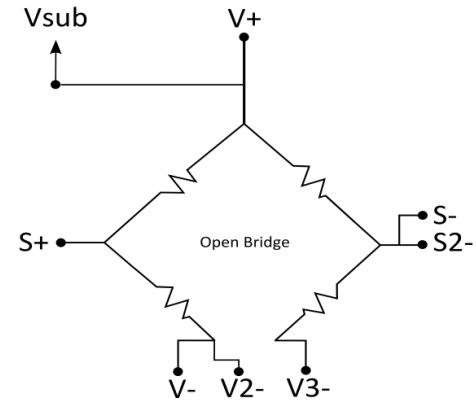
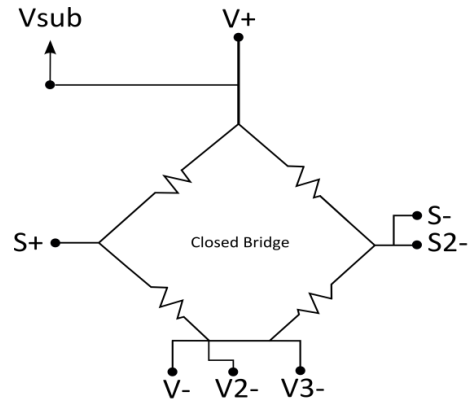
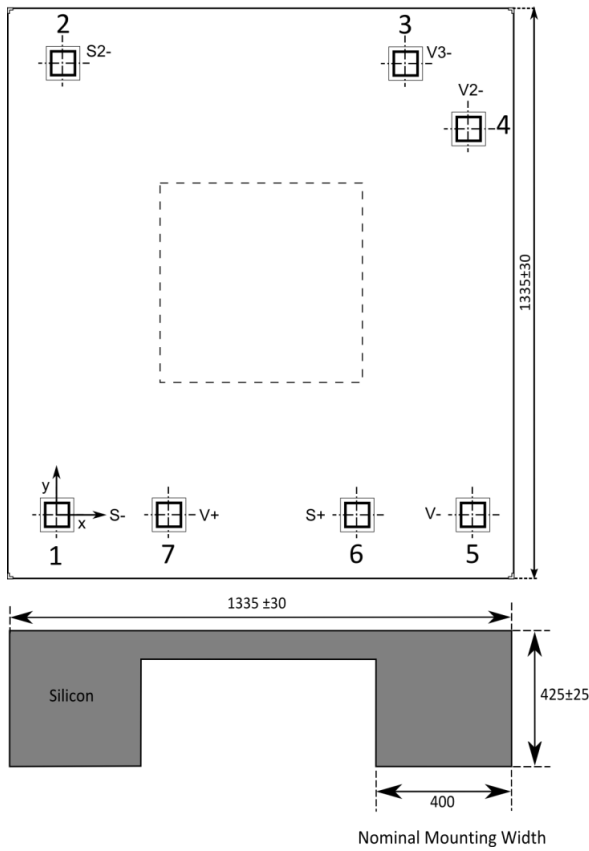
Notes:

- c) Tested on a sample basis
- d) Determined by measurements taken over -40°C to 150°C
- e) Defined as best fit straight line.
- f) Topside linearity is with the highest pressure applied to the topside of the die
- g) Backside linearity is with the highest pressure applied to the backside of the die

SM30F Diagrams & Dimensions

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All dimensions are in micron.

Bond pad opening size = 90x90 µm

Typical operation						
PAD #	PAD DESCRIPTION	PAD LABEL	TYPE	VALUE	Coordinate X-Axis (µm)	Coordinate Y-Axis (µm)
1	Negative Sensor Output	S-	- Analog Output	-	0	0
2	Negative Sensor Output	S2-	- Analog Output	-	0	1100
3	Negative Supply Voltage	V3-	Power	0 V	890	1100
4	Negative Supply Voltage	V2-	Power	0 V	1100	890
5	Negative Supply Voltage	V-	Power	0 V	1100	0
6	Positive Sensor Output	S+	+ Analog Output	-	840	0
7	Positive Supply Voltage	V+	Power	+5 V	260	0

Notes:

- Closed bridge configuration: Pads 3, 4, & 5 are connected
- Open bridge configuration: Pads 4 & 5 are connected, and pad 3 is the second negative supply voltage connection

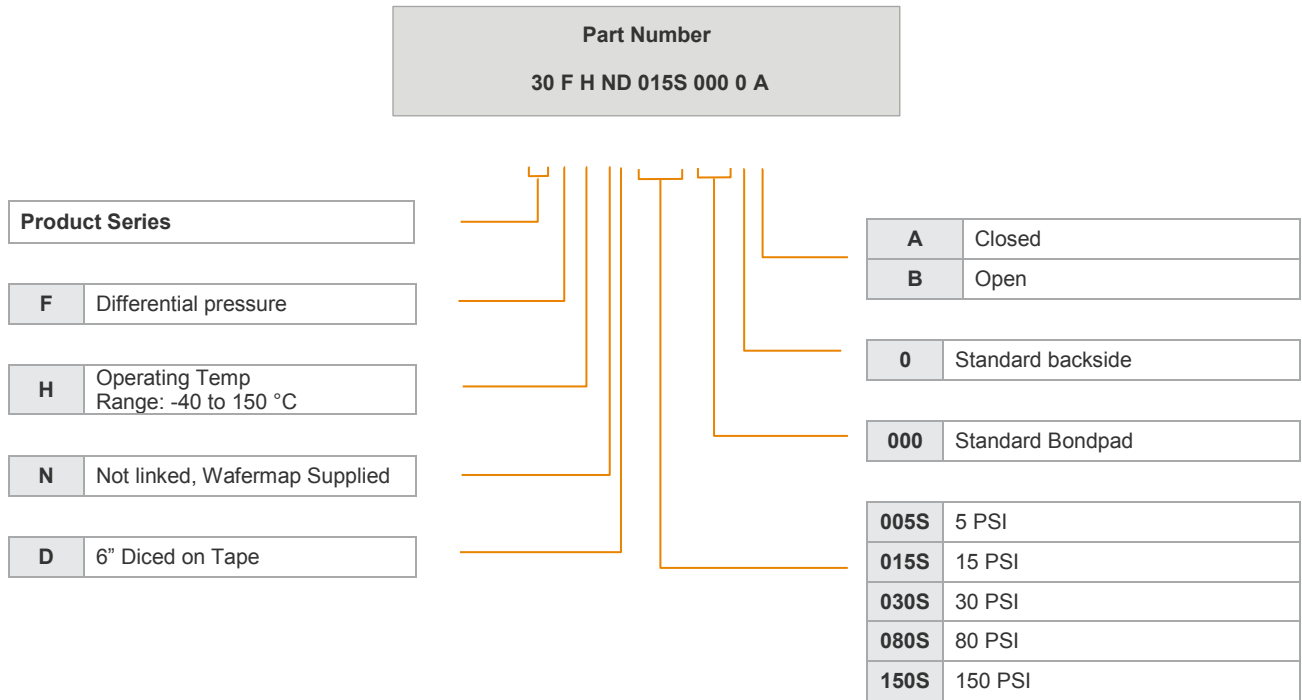
Ordering Information

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Order Code	Legacy Product Number	Full-Scale Pressure Range	Pressure type	Configuration	Minimum Order Quantity
30F-HND-005S-0000A 30F-HND-005S-0000B	30D-HND-005S-0000A 30D-HND-005S-0000B	5 PSI	Differential / Gauge	Closed bridge, 6" wafer diced on tape Open bridge, 6" wafer diced on tape	1 Wafer (1 wafer = 6,000 ±10%)
30F-HND-015S-0000A 30F-HND-015S-0000B	30D-HND-015S-0000A 30D-HND-015S-0000B	15 PSI		Closed bridge, 6" wafer diced on tape Open bridge, 6" wafer diced on tape	
30F-HND-030S-0000A 30F-HND-030S-0000B	30D-HND-030S-0000A 30D-HND-030S-0000B	30 PSI		Closed bridge, 6" wafer diced on tape Open bridge, 6" wafer diced on tape	
30F-HND-080S-0000A 30F-HND-080S-0000B	30D-HND-080S-0000A 30D-HND-080S-0000B	80 PSI		Closed bridge, 6" wafer diced on tape Open bridge, 6" wafer diced on tape	
30F-HND-150S-0000A 30F-HND-150S-0000B	30D-HND-150S-0000A 30D-HND-150S-0000B	150 PSI		Closed bridge, 6" wafer diced on tape Open bridge, 6" wafer diced on tape	

Part numbering key



Qualification standards

REACH Compliant

RoHS Compliant

PFOS/PFOA Compliant

For qualification specifications, please contact TE connectivity



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Tel +1 408 577 0100
customercare.mlpt@te.com

te.com

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